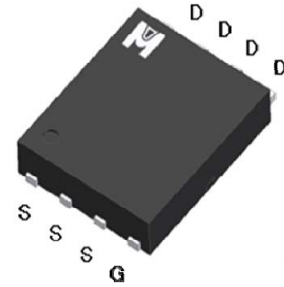


N-Channel Logic Level Enhancement Mode Field Effect Transistor

Product Summary:

BV_{DSS}	40V
$R_{DS(on)}$ (MAX.)	4m Ω
I_D	80A



UIS, Rg 100% Tested

Pb-Free Lead Plating & Halogen Free



ABSOLUTE MAXIMUM RATINGS ($T_A = 25\text{ }^\circ\text{C}$ Unless Otherwise Noted)

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNIT
Gate-Source Voltage		V_{GS}	± 30	V
Continuous Drain Current	$T_C = 25\text{ }^\circ\text{C}$	I_D	80	A
	$T_C = 100\text{ }^\circ\text{C}$		48	
Pulsed Drain Current ¹		I_{DM}	160	
Avalanche Current		I_{AS}	80	
Avalanche Energy	$L = 0.1\text{mH}, I_D=80\text{A}, R_G=25\Omega$	E_{AS}	320	mJ
Repetitive Avalanche Energy ²	$L = 0.05\text{mH}$	E_{AR}	160	
Power Dissipation	$T_C = 25\text{ }^\circ\text{C}$	P_D	50	W
	$T_C = 100\text{ }^\circ\text{C}$		20	
Operating Junction & Storage Temperature Range		T_{j}, T_{stg}	-55 to 150	$^\circ\text{C}$

100% UIS testing in condition of $V_D=20\text{V}$, $L=0.1\text{mH}$, $V_G=10\text{V}$, $I_L=50\text{A}$, Rated $V_{DS}=40\text{V}$ N-CH

THERMAL RESISTANCE RATINGS

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Case	$R_{\theta JC}$		2.5	$^\circ\text{C} / \text{W}$
Junction-to-Ambient	$R_{\theta JA}$		50	

¹Pulse width limited by maximum junction temperature.

²Duty cycle $\leq 1\%$

³50 $^\circ\text{C} / \text{W}$ when mounted on a 1 in² pad of 2 oz copper.

ELECTRICAL CHARACTERISTICS ($T_J = 25\text{ }^\circ\text{C}$, Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	40			V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	2	3	4	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0V, V_{GS} = \pm 30V$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 32V, V_{GS} = 0V$			1	μA
		$V_{DS} = 30V, V_{GS} = 0V, T_J = 125\text{ }^\circ\text{C}$			25	
On-State Drain Current ¹	$I_{D(ON)}$	$V_{DS} = 10V, V_{GS} = 10V$	80			A
Drain-Source On-State Resistance ¹	$R_{DS(ON)}$	$V_{GS} = 10V, I_D = 24A$		3.5	4.0	$m\Omega$
		$V_{GS} = 7V, I_D = 24A$		5.2	6.5	
Forward Transconductance ¹	g_{fs}	$V_{DS} = 5V, I_D = 24A$		35		S
DYNAMIC						
Input Capacitance	C_{iss}	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$		3970		pF
Output Capacitance	C_{oss}			650		
Reverse Transfer Capacitance	C_{rss}			597		
Gate Resistance	R_g	$V_{GS} = 15mV, V_{DS} = 0V, f = 1MHz$		1.7		Ω
Total Gate Charge ^{1,2}	Q_g	$V_{DS} = 20V, V_{GS} = 10V,$ $I_D = 20A$		83.6		nC
Gate-Source Charge ^{1,2}	Q_{gs}			18.7		
Gate-Drain Charge ^{1,2}	Q_{gd}			34.5		
Turn-On Delay Time ^{1,2}	$t_{d(on)}$	$V_{DS} = 20V,$ $I_D = 20A, V_{GS} = 10V, R_{GS} = 6\Omega$		50		nS
Rise Time ^{1,2}	t_r			120		
Turn-Off Delay Time ^{1,2}	$t_{d(off)}$			75		
Fall Time ^{1,2}	t_f			150		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ($T_C = 25\text{ }^\circ\text{C}$)						
Continuous Current	I_S				80	A
Pulsed Current ³	I_{SM}				160	
Forward Voltage ¹	V_{SD}	$I_F = 24A, V_{GS} = 0V$			1.3	V
Reverse Recovery Time	t_{rr}	$I_F = 24A, di_F/dt = 100A / \mu S$		30		nS
Reverse Recovery Charge	Q_{rr}				200	

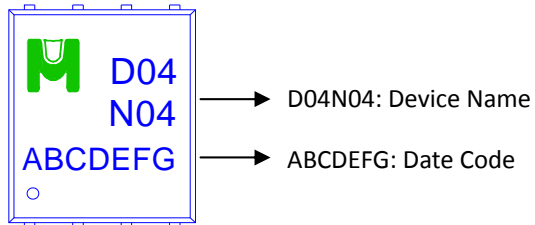
¹Pulse test : Pulse Width $\leq 300\ \mu\text{sec}$, Duty Cycle $\leq 2\%$.

²Independent of operating temperature.

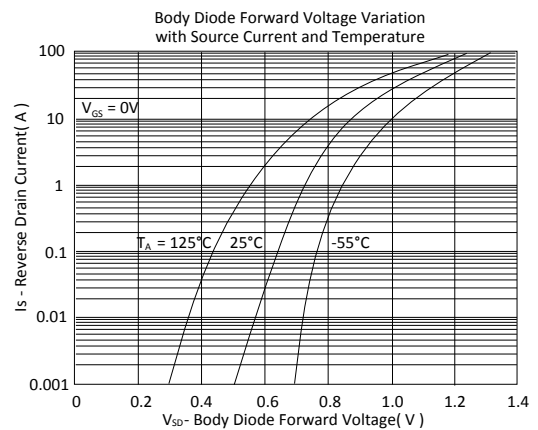
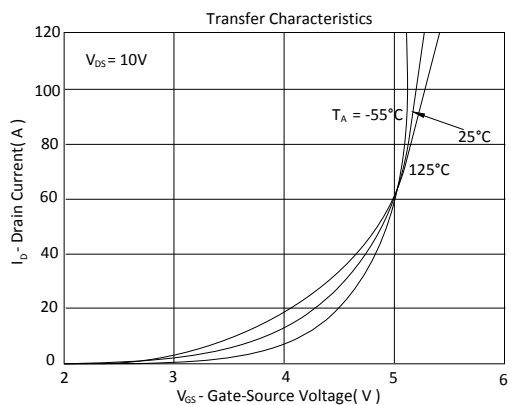
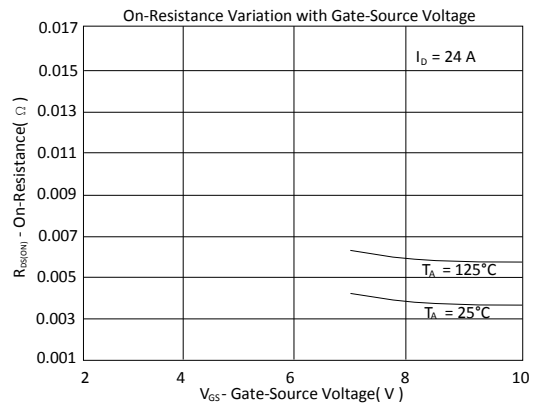
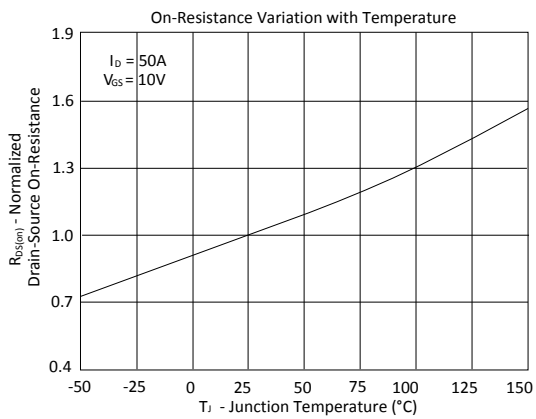
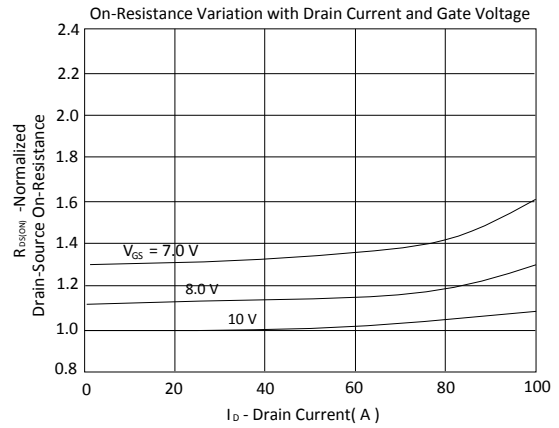
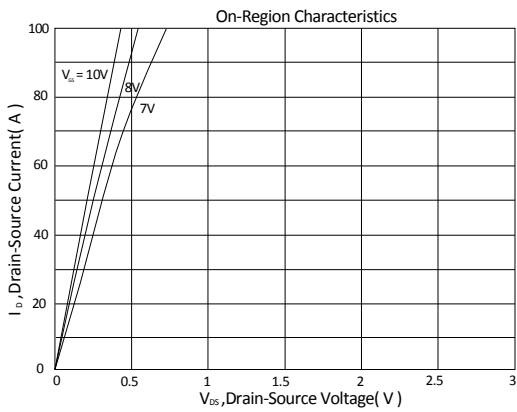
³Pulse width limited by maximum junction temperature.

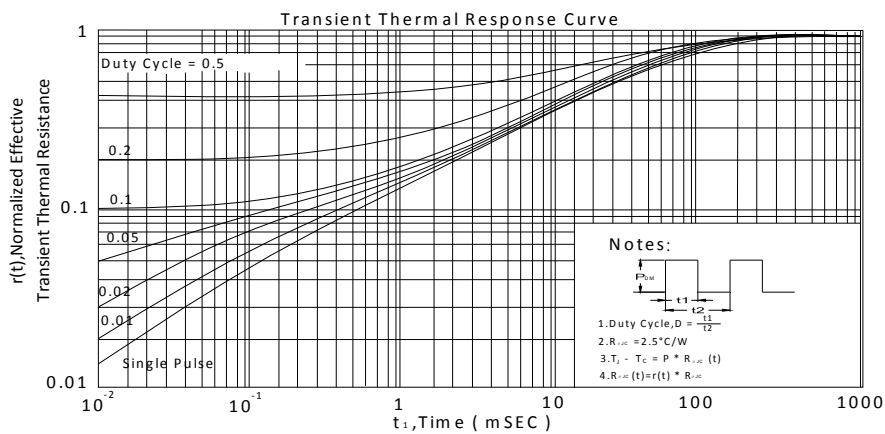
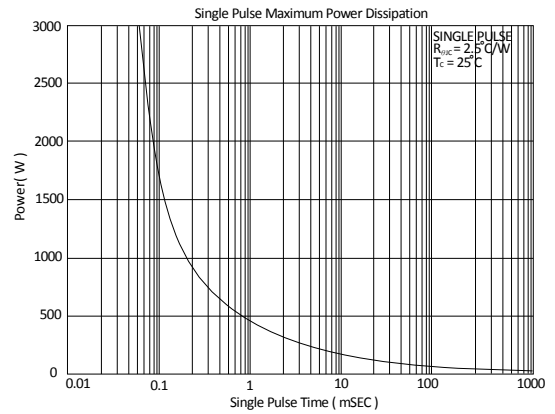
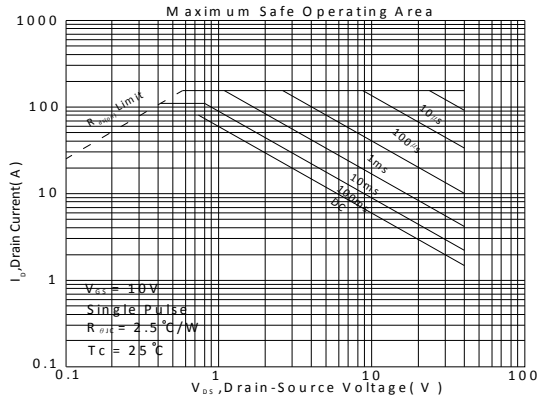
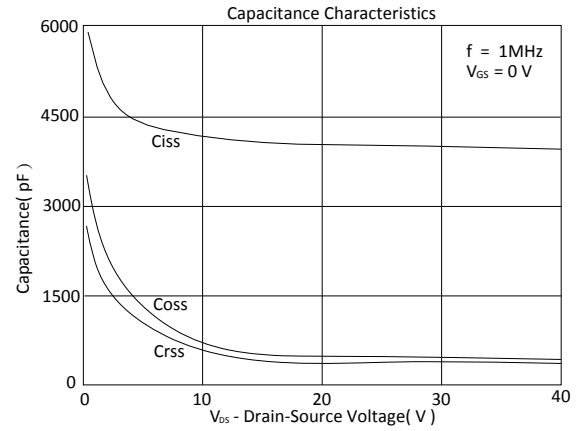
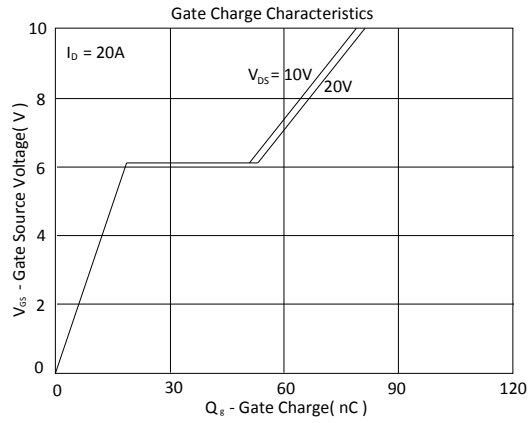
Ordering & Marking Information:

Device Name: EMD04N04H for EDFN 5 x 6



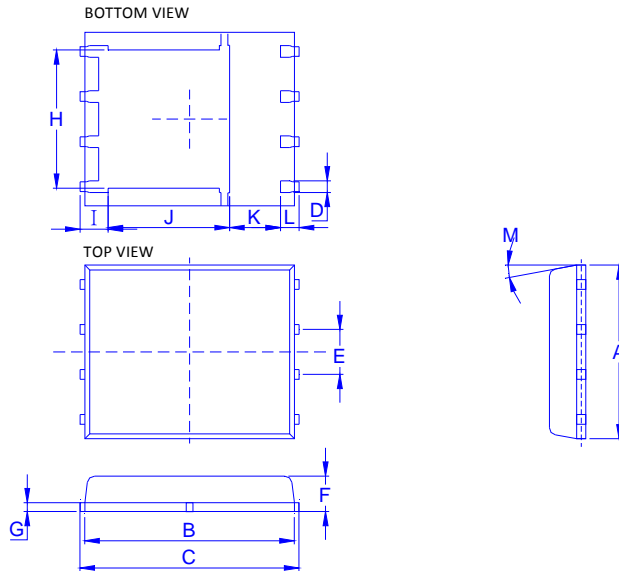
TYPICAL CHARACTERISTICS







Outline Drawing



Dimension in mm

Dimension	A	B	C	D	E	F	G	H	I	J	K	L	M
Min.	4.80	5.50	5.90	0.3		0.85	0.15	3.67	0.41	3.00	0.94	0.45	0°
Typ.					1.27								
Max.	5.30	5.90	6.15	0.51		1.20	0.30	4.54	0.85	3.92	1.7	0.71	12°

Recommended minimum pads

